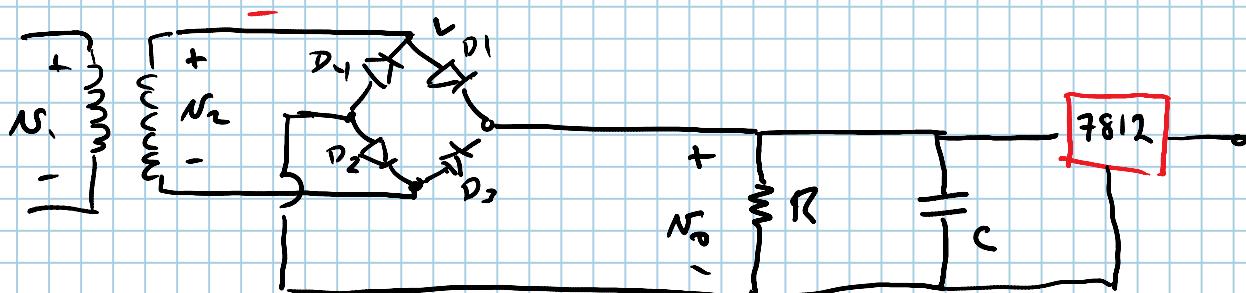
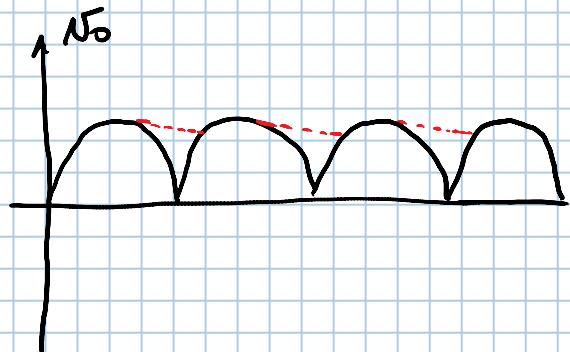
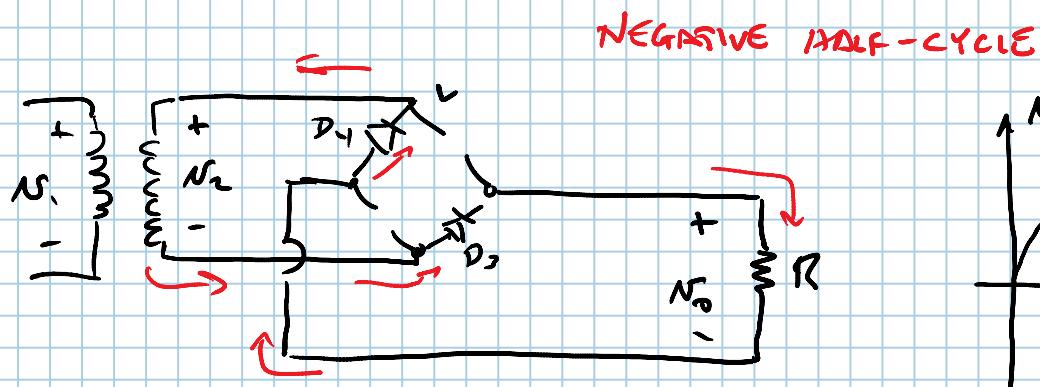
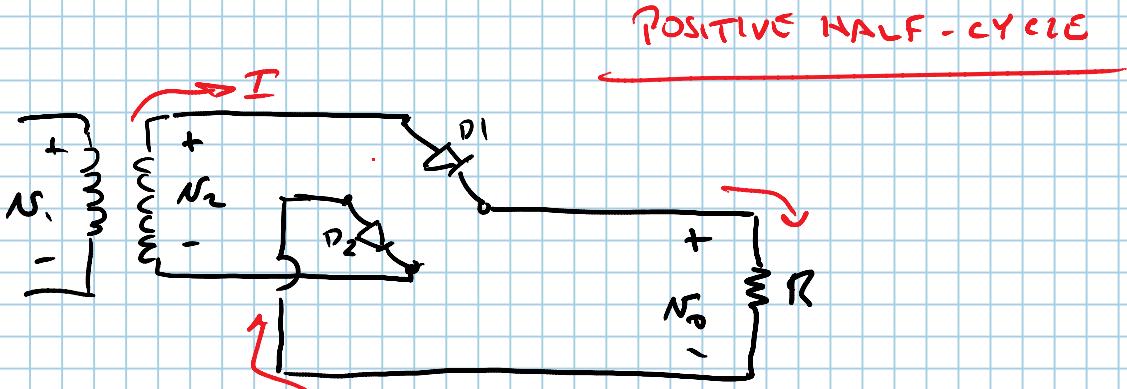
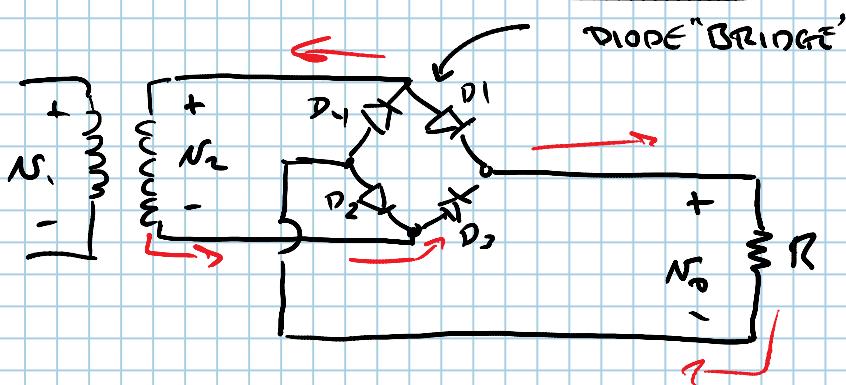
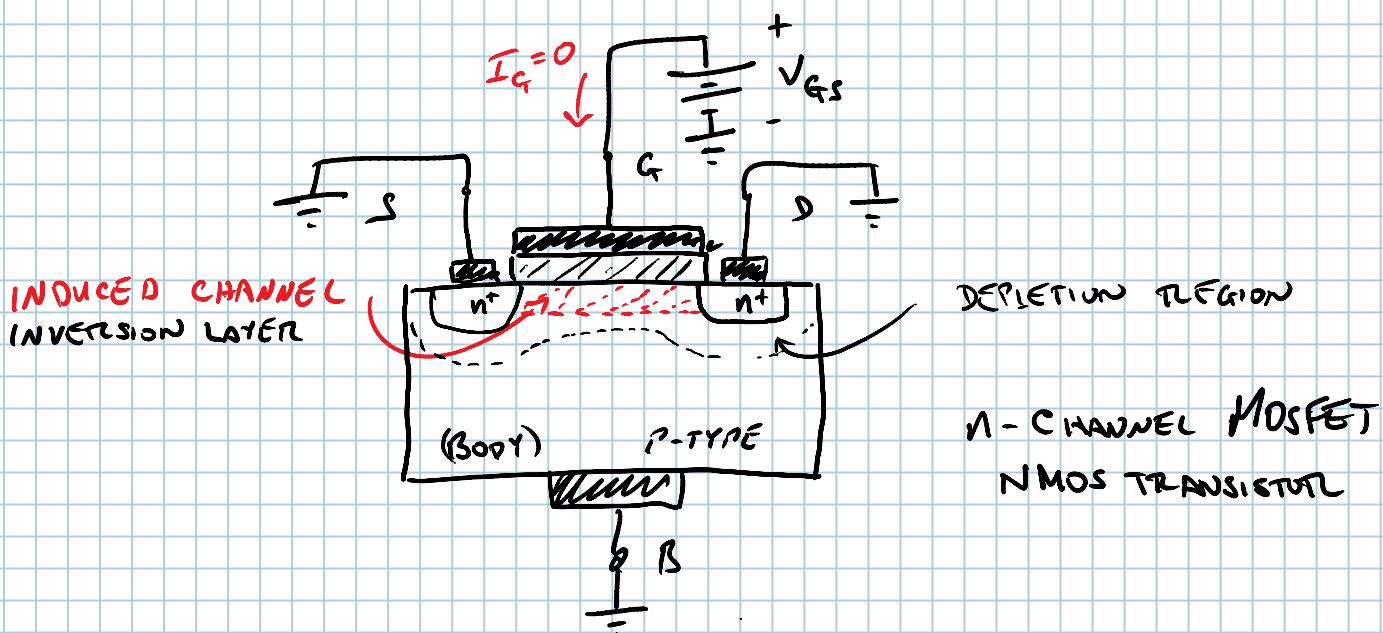
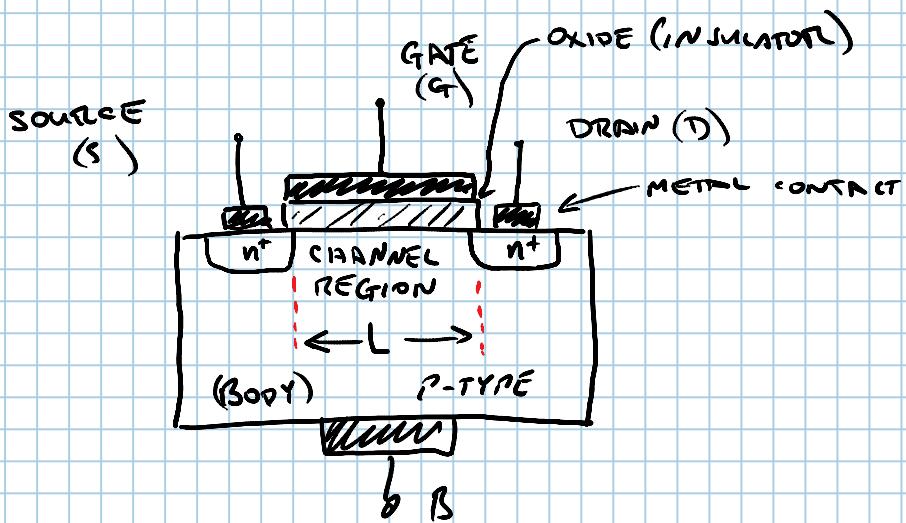


Full-Wave Rectification II

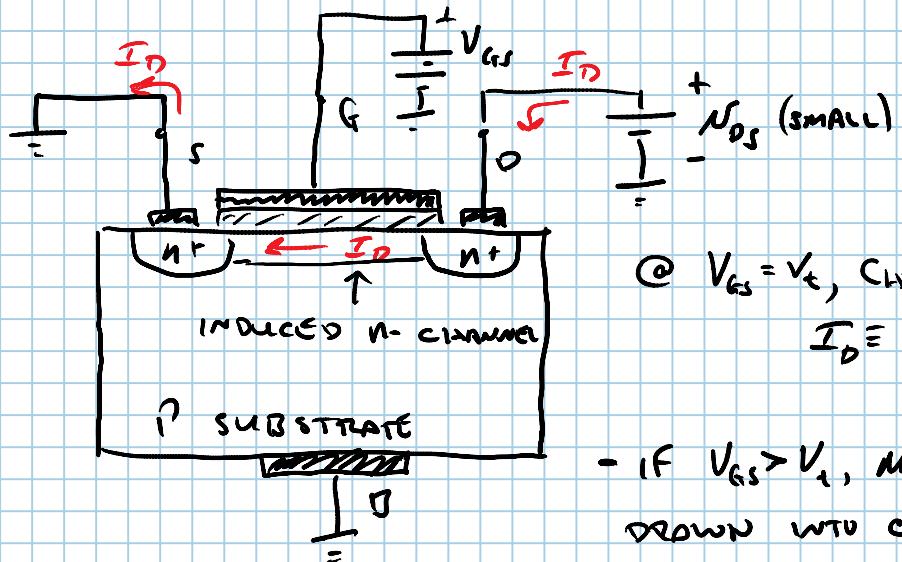


Metal Oxide Semiconductor Field-Effect Transistors (MOSFETs)



$V_t \equiv$ THRESHOLD VOLTAGE, THE VALUE OF V_{GS} AT WHICH ENOUGH MOBILE ELECTRONS ACCUMULATE IN THE CHANNEL TO SUPPORT CONDUCTION.

$V_t > 0$ FOR NMOS

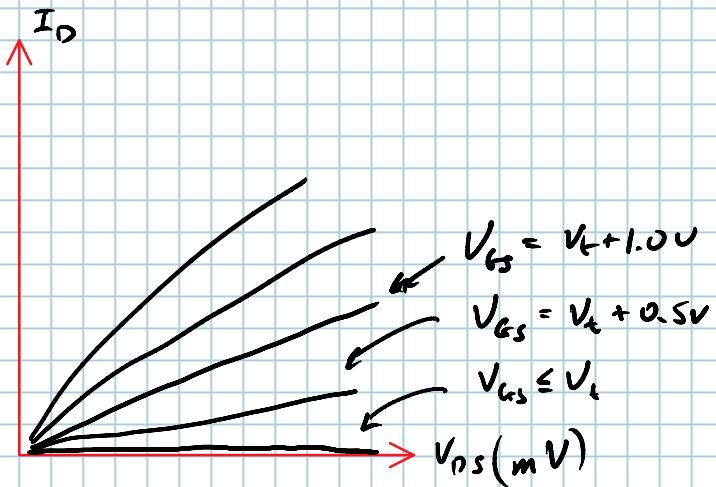


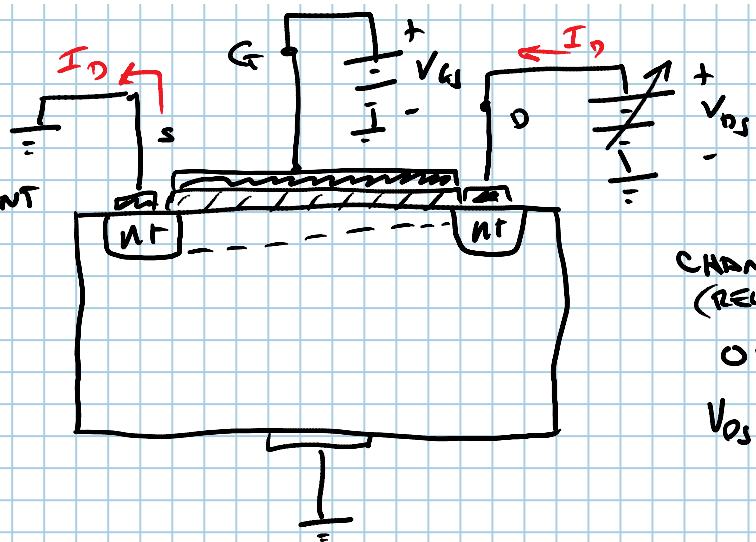
④ $V_{GS} = V_t$, CHANNEL IS JUST INDUCED,
 $I_D \approx \text{NEGIGIBLE}$

- IF $V_{GS} > V_t$, MORE ELECTRONS ARE DRAWN INTO CHANNEL, CHANNEL IS "DEEPER", INCREASED CONDUCTANCE,
 \Rightarrow REDUCED RESISTANCE.

- CHANNEL CONDUCTANCE IS PROPORTIONAL TO THE

$$\text{"EXCESS GATE VOLTAGE"} = V_{GS} - V_t$$





CHANNEL VOLTAGE,
(RELATIVE TO SOURCE)

0V @ SOURCE END

V_{DS} @ DRAIN END

- VOLTAGE BETWEEN GATE & POINTS ALONG CHANNEL:

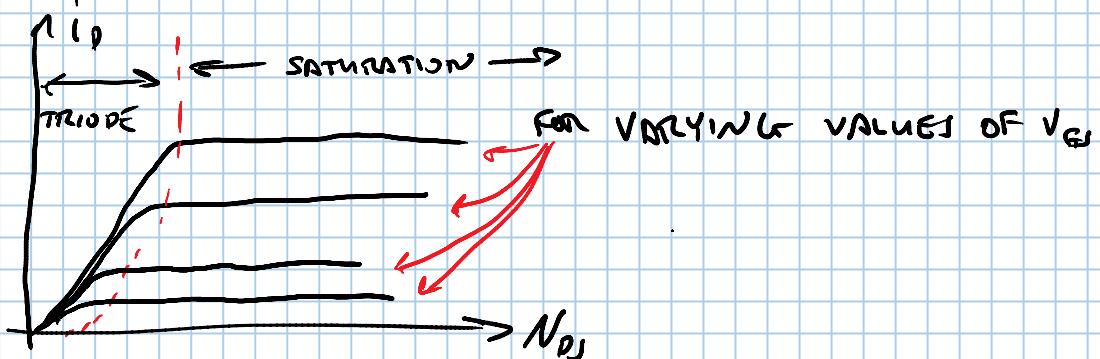
$V_{GS} = 0$ @ SOURCE

$V_{GS} - V_{DS}$ @ DRAIN

- WHEN N_{DS} INCREASED TO THE VALUE THAT REDUCES THE VOLTAGE BETWEEN GATE & CHANNEL @ THE DRAIN END TO V_t ,

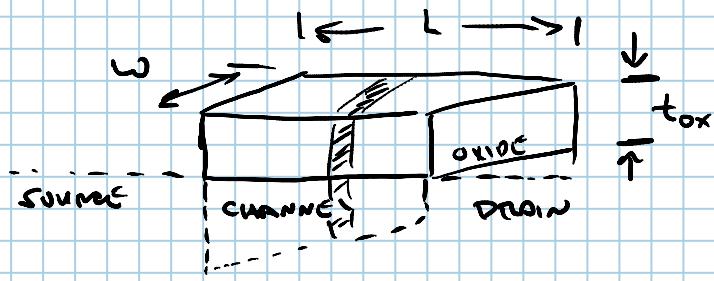
$$N_{GS} = V_t \text{, OR } V_{GS} - V_{DS} = V_t$$

$$\text{OR } N_{DS} = N_{GS} - V_t \quad \otimes$$



@ $N_{DS} = N_{GS} - V_t$, - CHANNEL DEPTH (@ DRAIN END) IS ALMOST ZERO
- CHANNEL IS SAID TO BE "PINCHED-OFF".

$$I_D = \text{SATURATED}, N_{DS} = N_{DS,SAT} = N_{GS} - V_t$$



$$C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$$

ϵ_{ox} = PERMITTIVITY OF OXIDE LAYER

t_{ox} = THICKNESS OF OXIDE LAYER

$$\textcircled{R} \quad i_D = \mu_n C_{ox} \left(\frac{W}{L} \right) \left[(V_{GS} - V_t) N_{DS} - \frac{1}{2} N_{DS}^2 \right] \quad (\text{TRIODE REGION})$$

IF $N_{DS} = N_{GS} - V_t \Rightarrow$ PINCHED-OFF, IN SATURATION REGION.

$$i_D = \mu_n C_{ox} \left(\frac{W}{L} \right) \frac{1}{2} (V_{GS} - V_t)^2 \quad (\text{SATURATION REGION OPERATION})$$

(μ_n = ELECTRON MOBILITY)

$$\mu_n C_{ox} = k_n' \left(\frac{A}{V^2} \right) \quad \text{PROCESS TRANSDUCTANCE PARAMETER}$$

$$\therefore i_D = k_n' \left(\frac{W}{L} \right) \left[(V_{GS} - V_t) N_{DS} - \frac{1}{2} N_{DS}^2 \right] \quad (\text{TRIODE REGION})$$

$$i_D = \frac{1}{2} k_n' \left(\frac{W}{L} \right) (V_{GS} - V_t)^2 \quad (\text{SATURATION REGION})$$

EXAMPLE 5.1, pg 243

$$L_{mn} = 0.4 \text{ mm}$$

$$t_{ox} = 8 \text{ nm}$$

$$M_n = 450 \frac{\text{cm}^2}{\text{V}\cdot\text{s}}$$

$$V_t = 0.7 \text{ V}$$

a) FWD $C_{ox} + k_n'$

$$C_{ox} = \frac{\epsilon_{ox}}{t_{ox}} = \frac{3.45 \times 10^{-11} \text{ F/m}}{8 \times 10^9 \text{ m}} = 4.31 \times 10^{-20} \text{ F/m}^2 = 4.31 \frac{\text{fF}}{\text{mm}^2}$$

$$k_n' = M_n C_{ox} = \left(450 \frac{\text{cm}^2}{\text{V}\cdot\text{s}}\right) \left(4.31 \times 10^{-20} \frac{\text{F}}{\text{mm}^2}\right)$$

$$k_n' = \left(450 \times 10^8 \frac{\text{mm}^2}{\text{V}\cdot\text{s}}\right) \left(4.31 \frac{\text{fF}}{\text{mm}^2}\right) = \boxed{194 \frac{\mu\text{A}}{\text{V}^2}}$$

b) $\frac{w}{l} = \frac{8 \text{ mm}}{0.8 \text{ mm}}$

$$V_{GS} = V_{GS} - V_t$$

k_m

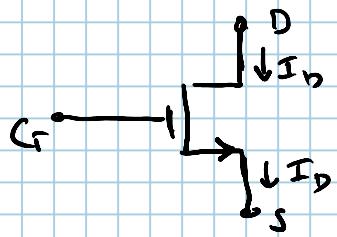
$$I_D = k_m \frac{w}{l} C_{ox} \left(\frac{V_{GS} - V_t}{2}\right)^2$$

$$100 \mu\text{A} = \frac{1}{2} \left(194 \frac{\mu\text{A}}{\text{V}^2}\right) \left(\frac{0}{0.8}\right) \left(V_{GS} - V_t\right)^2 \Rightarrow \left(V_{GS} - V_t\right)^2 = 103.09 \times 10^{-3} \text{ V}^2$$

$$V_{GS} - V_t = 0.321 \text{ V}$$

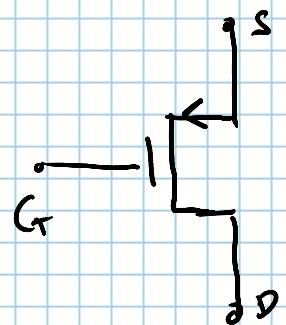
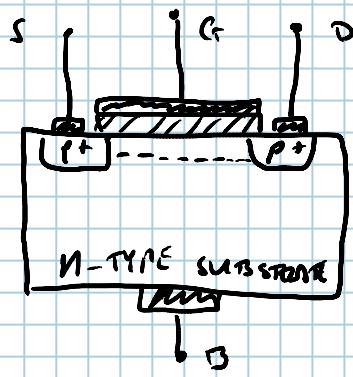
$$\boxed{V_{GS} = 1.021 \text{ V}}$$

NMOS TRANSISTOR

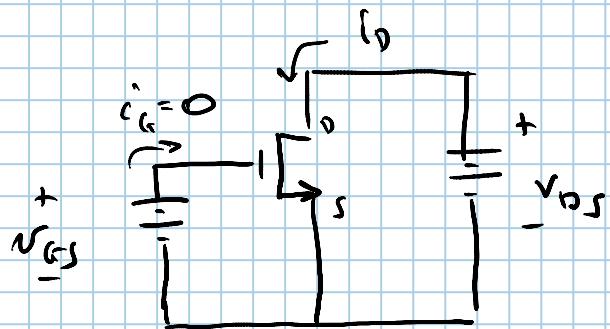


n-channel MOSFET

- n - type substrate
- drain & source = p+ mat'l \Rightarrow holes are majority charge carriers.
- operation is similar to NMOS except: - N_{G_S} & N_{D_S} are neg.
- V_G is neg.



$i_o - N_{DS}$ characteristics (NMOS)



$$N_{DS} < N_{GS} - V_t$$

